



NOTES:

- PLATING THICKNESS:
ELECTRO Ni : 1.27~8.89 MICRON. (SOLDER PADS)
ELECTRO Au : 0.70~1.20 MICRON. (SOLDER PADS)
- CONNECTION:
(1-6-9-VCC), (2-XIN), (3-XOUT), (4-10-GND-S/R-D/A), (5-OE), (7-OUTN), (8-OUT), (NC-NC)
- CAMBER : 50.00 MICRON MAX.
- EXPOSURE OF CERAMIC SURFACE OCCURRED BY MISALIGNMENT OF THE UPPER LAYER, SHALL BE ALLOWED.
- PART TO BE SHOWN AS SIDE METALLIZED PATTERN.
- STRESS RELAXATION DESIGN SHALL BE APPLIED ON THIS ITEM.
- SEALING METHOD OF THIS PRODUCT SHALL BE SBAM WBLD.

TOLERANCE	REVISION	SBB ATTACHED EXCEPTIONS SHEET.				TITLE	
XX ±1% XXX N.L.T.±0.13 ANGLES	SCALE	DIMENSION	PROJECTION	CUSTOMER DWG NO.	REV.	CF5034 PKG	
	15 : 1	mm	3rd			PART NO.	REV.
MATERIAL	APPROVED	CHECKED	ENGRG	CHECKED	DESIGNED	S5070DCK3	1
90%MIN.A1203 (INA-311B BLACK)	Sumida	Tokushige	Ohba	Kumura	Handa	DWG NO.	SHT/OF 1/6
	Jul.28.04	Jul.28.04	Jul.28.04	Jul.28.04	Jul.28.04		